DS22W THRU DS220W

Surface Mount Schottkay B rrier Rectifier

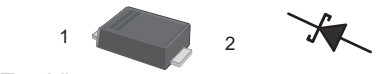
Reverse Voltage - 20 to 200 V
Forward Current - 2.0A

Features

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Top View

Marking Code : DS22W ---S22
DS24W : ---S24
DS26W : ---S26
DS28W : ---S28
DS210W : ---S210
DS212W : ---S212
DS215W : ---S215
DS220W : ---S220

Weight : 17mg , 0.0006 oz
Simplified outline SOD-123FL and symbol

Absolute Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

Parameter	Symbols	DS22W	DS24W	DS26W	DS28W	DS210W	DS212W	DS215W	DS220W	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	20	40	60	80	100	120	150	200	V
Maximum RMS voltage	V_{RMS}	14	28	42	56	70	84	105	140	V
Maximum DC Blocking Voltage	V_{DC}	20	40	60	80	100	120	150	200	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	2.0								A
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	50				40				A
Max Instantaneous Forward Voltage at 2 A	V_F	0.55		0.70		0.85		0.95		V
Maximum DC Reverse Current T_a = 25°C at Rated DC Reverse Voltage T_a =100°C	I_R	0.5 10			0.3 5					mA
Typical Junction Capacitance 1)	C_j	220		80						pF
Operating Junction Temperature Range	T_j	-55 ~ +125								°C
Storage Temperature Range	T_{stg}	-55 ~ +150								°C

1) Measured at 1MHz and applied reverse voltage of 4 V D.C.

Fig.1 Forward Current Derating Curve

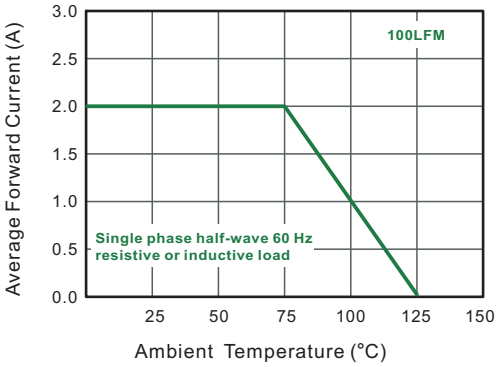


Fig.2 Typical Reverse Characteristics

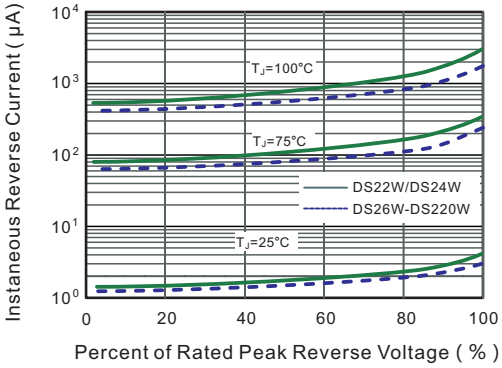


Fig.3 Typical Forward Characteristic

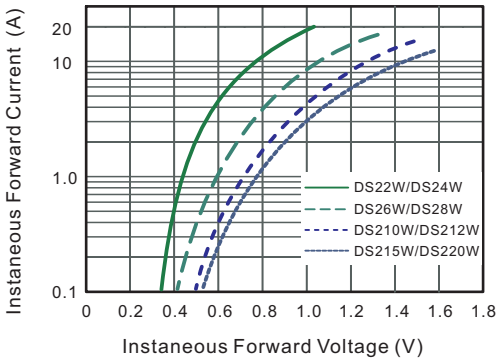


Fig.4 Typical Junction Capacitance

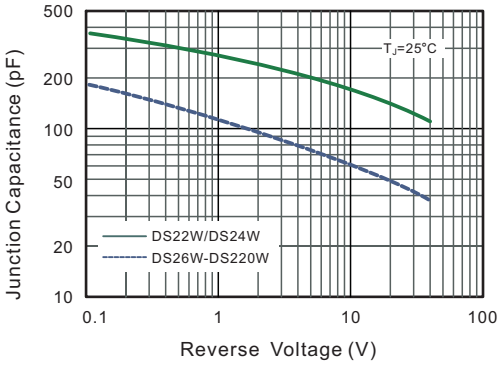
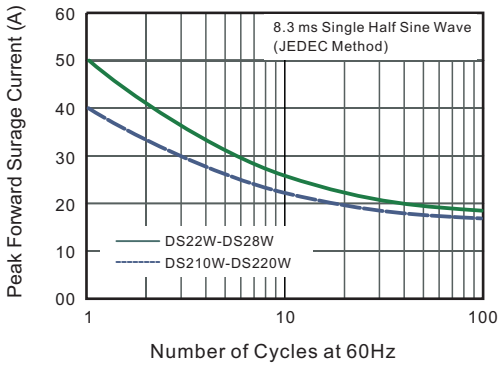
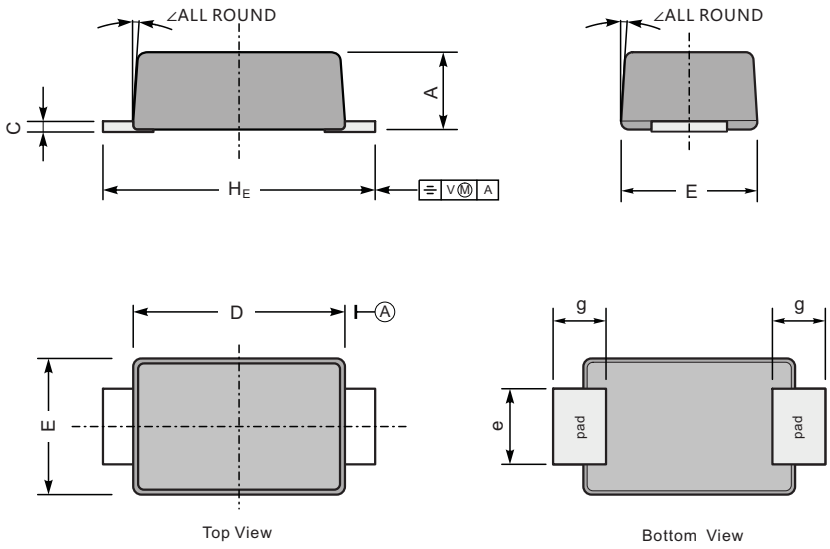


Fig.5 Maximum Non-Repetitive Peak Forward Surage Current



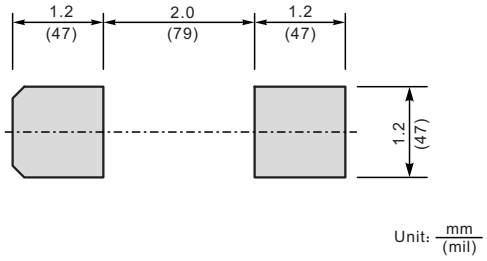
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads SOD123FL

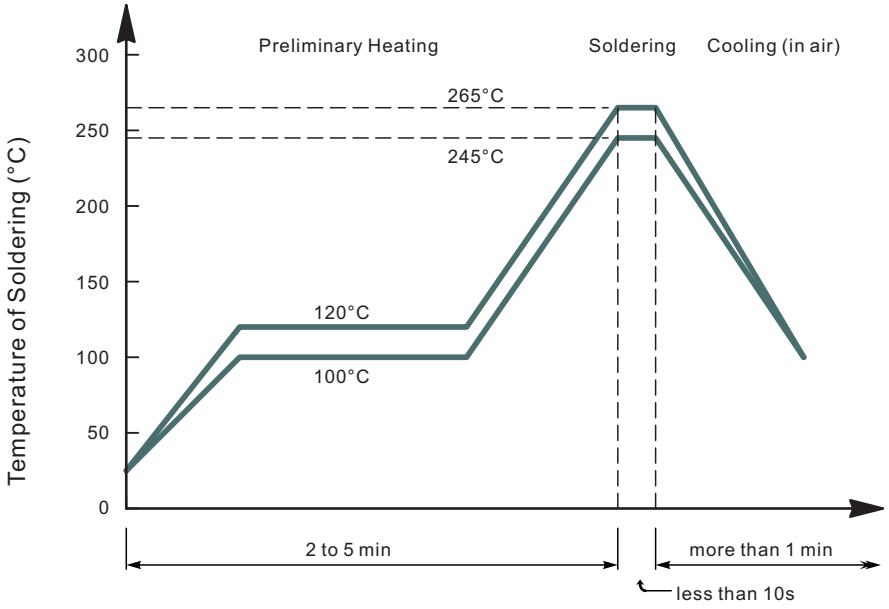


UNIT		A	C	D	E	e	g	H_E	∠
mm	max	1.1	0.20	2.9	1.9	1.1	0.9	3.8	7°
	min	0.9	0.12	2.6	1.7	0.8	0.7	3.5	
mil	max	43	7.9	114	75	43	35	150	
	min	35	4.7	102	67	31	28	138	

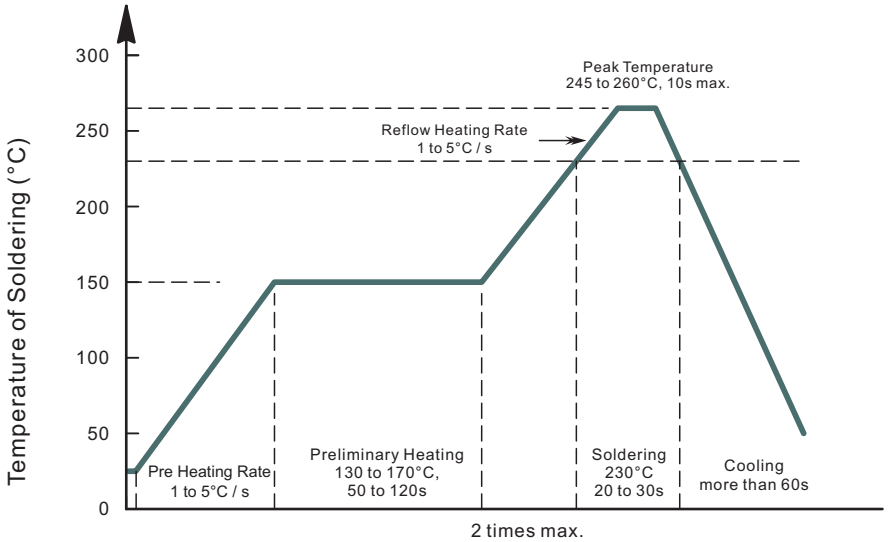
The recommended mounting pad size



• **Recommended condition of flow soldering**



• **Recommended condition of reflow soldering**



Recommended peak temperature is over 245 °C. If peak temperature is below 2 45 ° C , you may adjust the following parameters; time length of peak temperature (longer), time length of soldering (longer), thickness of solder paste (thicker)

• **Condition of hand soldering**
Temperature: 350°C
Time: 3s max.
Times: one time

• **Remark:**
Lead free solder paste (96.5Sn/3.0Ag/0.5Cu)